

4226657/A 03/2021

NOTES:

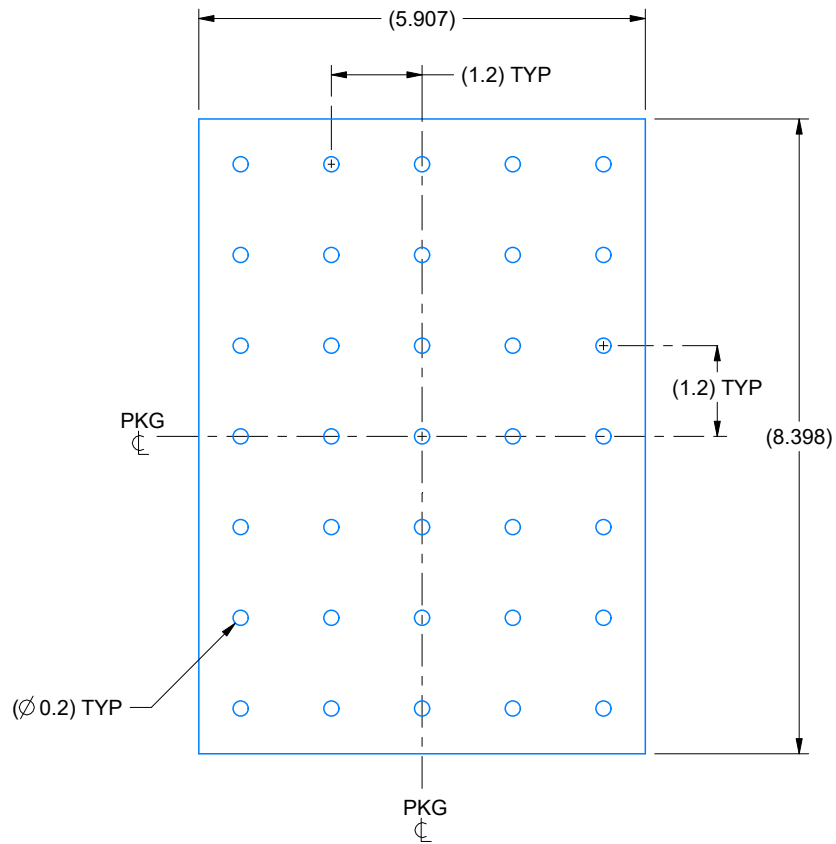
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. Lid is connected to Heatsink and pin 6
4. The terminals are gold plated.

EXAMPLE BOARD LAYOUT

HBL0014A

CFP - 2.527 mm max height

CERAMIC DUAL FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:10X

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REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2193915	03/24/2021	R. RAZAK / ANIS FAUZI

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